

# Bill of Materials

TI DESIGNS  
Part # 7355  
Literature #PMP

COUNT	RefDes	Value	Description	Size	Part Number	MFR
1	C18	100pF	Capacitor, Ceramic, 16V, X7R, 10%	603	STD	Std
1	C19	6800pF	Capacitor, Ceramic, 16V, X7R, 10%	603	STD	Std
1	C21	0.047uF	Capacitor, Ceramic, 16V, X7R, 10%	603	STD	Std
1	C20	0.1uF	Capacitor, Ceramic, 16V, X7R, 10%	603	STD	Std
1	C15	0.22uF	Capacitor, Ceramic, 25V, X7R, 10%	805	STD	Std
4	C1, C2, C3, C4	0.1uF	Capacitor, Ceramic, 100V, X7R, 10%	603	STD	Std
2	C22, C28	1uF	Capacitor, Ceramic, 10V, X5R, 20%	603	STD	Std
1	C7	680pF	Capacitor, Ceramic, 50V, C0G, 10%	805	STD	Std
4	C17, C24, C25, C26	1000pF	Capacitor, Ceramic, 100V, X7R, 10%	805	STD	Std
2	C11, C23	0.1uF	Capacitor, Ceramic, 100V, X7R, 10%	805	STD	Std
2	C9, C10	2.2uF	Capacitor, Ceramic, 100V, X7R, 10%	1210	Std	Std
2	C12, C13	47uF	Capacitor, Ceramic, 10V, X5R, 20%	1210	C3225X5R1A476M	TDK
1	C5	1000pF	Capacitor, Ceramic Chip, 2KV, 10%	1808	Std	Std
2	C6, C27	2200pF	Capacitor, Ceramic, 2KV, X7R, 20%	1812	Std	TDK
1	C16	10uF	Capacitor, Aluminum, 25V, 20%	4x5.8mm	EEEFK1E100R	Panasonic
1	C14	100uF	Capacitor, Aluminum, 6.3V, 20%	6.3x5.8mm	EEEFK0J101P	Panasonic
1	C8	22uF	Capacitor, Aluminum Electrolytic, 100V, 20%	8x10.2mm	EEEFK2A220P	Panasonic
1	D1		Diode, Transient Voltage Suppressor, 400W, 58V	SMA	SMAJ58A	Diodes, Inc
1	D10		Diode, Switching, 200mA, 75V, 225mW	SOT-23	BAS16	On Semi
1	D12		Diode, Dual Schottky, 200mA, 30V	SOT23	BAT54S	Diodes, Inc
2	D2, D3		Bridge Rectifier, 100V, 0.8A, Glass Passivated, SMD	MINI DIP4	HD01	Diodes, Inc
1	D4		Diode, Schottky, 5A, 40V	SMC	B540	Diodes, Inc
2	D8, D14		Diode, Rectifier, 1A, 200V	SMA	MURA120	On Semi
4	FB1, FB2, FB3, FB4	220	Bead, Ferrite, SMT, 220 Ohms, 3A	805	MPZ2012S221A	TDK
2	J1, J2		Connector, Jack, Modular, 8 POS	0.705 x 0.820 inch	520252	AMP
2	J3, J6		Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25 inch	ED555/2DS	OST
1	L1	10uH	Inductor, SMT, 750mA, 350 milliohm	4x4mm	LPS4012-103ML	Coilcraft
1	L2	1uH	Inductor, SMT, 2.4A, 60 milliohm	4x4mm	LPS4012-102NL	Coilcraft
1	Q2		MOSFET, N-ch, 150-V, 4.1A, 66 milliOhms	SO8	FDS2582	Fairchild
1	R14	0	Resistor, Chip, 1/16W, 1%	603	STD	Std

COUNT	RefDes	Value	Description	Size	Part Number	MFR
1	R13	10	Resistor, Chip, 1/16W, 1%	603	STD	Std
4	R1, R2, R3, R4	75	Resistor, Chip, 1/16W, 1%	603	STD	Std
1	R12	90.9	Resistor, Chip, 1/16W, 1%	603	STD	Std
1	R28	402	Resistor, Chip, 1/16W, 1%	603	STD	Std
2	R20, R22	1K	Resistor, Chip, 1/16W, 1%	603	STD	Std
1	R23	2K	Resistor, Chip, 1/16W, 1%	603	STD	Std
2	R16, R21	10K	Resistor, Chip, 1/16W, 1%	603	STD	Std
1	R24	14.3K	Resistor, Chip, 1/16W, 1%	603	STD	Std
1	R7	24.9K	Resistor, Chip, 1/16W, 1%	603	STD	Std
1	R27	39.2K	Resistor, Chip, 1/16W, 1%	603	STD	Std
1	R19	44.2K	Resistor, Chip, 1/16W, 1%	603	STD	Std
1	R10	59K	Resistor, Chip, 1/16W, 1%	603	STD	Std
1	R11	80.6K	Resistor, Chip, 1/16W, 1%	603	STD	Std
1	R26	392K	Resistor, Chip, 1/16W, 1%	603	STD	Std
1	R9	10	Resistor, Chip, 1/10W, 5%	805	STD	Std
1	R6	39K	Resistor, Chip, 1/10W, 5%	805	STD	Std
1	R18	0.39	Resistor, Chip, 1/2W, 1%	2010	STD	Std
1	R5	20	Resistor, Chip, 1/2W, 5%	2010	STD	Std
1	T1		XFMR, 1000 Base-T, Ratio 1:1	0.500 x 0.370 inch	H2019	Pulse
1	T2		Transformer, Flyback For PoE, 5V, 2A	0.700 x 0.530 inch	POE13P-50L	Coilcraft
		ALT T2	Transformer, Flyback For PoE, 5V, 2A	0.700 x 0.530 inch	RL-9982	Renco
1	U2		IC, Photocoupler, 3750VRMS, 80-160% CTR	MF4	TCMT1107	Vishay
1	U3		IC, Shunt Regulator, 1.24-V ref, 6-V, 10-mA, 1%	SOT23-5	TLV431ACDBVR	TI
1	U1		IC, IEEE 802.3af Integrated Primary Side Controller	TSSOP14	TPS23753APW	TI

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